

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (currently amended) A lead-frame configuration that is ~~in the form of a lead-frame strip~~~~strip-like in form~~, that has a frame base and that has a plurality of lead-frames that are connected to the frame base and that are situated next to one another in the longitudinal direction of the lead-frame strip, each of which lead-frames is intended to receive a chip wherein, each lead-frame has at least two connecting plates wherein there ~~being~~ is provided for the lead-frames that are situated next to one another in the longitudinal direction of the lead-frame strip a reinforcement strip that extends in the longitudinal direction of the lead-frame strip and is connected both to the frame base and to the connecting plates of each of the lead-frames that are situated next to one another in the longitudinal direction of the lead-frame strip, the connection being made by means of a layer of adhesive, wherein the reinforcement strip is formed by a fiber-reinforced film of plastics material and wherein the layer of adhesive is produced by means of an adhesive that is suitable for transmitting shear forces that may ~~possibly~~ occur in the region between the connecting plates on the one hand and the reinforcement strip on the other hand.
2. (original) A lead-frame configuration as claimed in claim 1, wherein at least one further layer is provided on the reinforcement strip formed by a fiber-reinforced film of plastics material.
3. (currently amended) A lead-frame configuration as claimed in claim 2, wherein at least one further layer is provided on the reinforcement strip formed by a fiber-reinforced film of plastics material, which at least one further layer belongs to the group of layers detailed below, which group comprises: a protective layer that is composed of metal, a damping layer that is composed of a damping material ~~and preferably of a paper-like material~~, and a fastening layer that is composed of a fastening material ~~and preferably of an adhesive material~~.

4. (currently amended) A module that is produced with the help of a lead-frame configuration and that has at least two connecting plates each of which is connected to a connecting contact of a chip, and that has a reinforcement ribbon that is connected to the connecting plates, the connection between the reinforcement ribbon and the connecting plates being made by means of a layer of adhesive, wherein the reinforcement ribbon is formed by a fiber-reinforced film of plastics material and wherein the layer of adhesive is produced by means of an adhesive that is suitable for transmitting shear forces that may ~~possibly~~ occur in the region between the connecting plates on the one hand and the reinforcement ribbon on the other hand.

5. (original) A module as claimed in claim 4, wherein at least one further layer is provided on the reinforcement ribbon formed by a fiber-reinforced film of plastics material.

6. (currently amended) A module as claimed in claim 5, wherein at least one further layer is provided on the reinforcement ribbon formed by a fiber-reinforced film of plastics material, which at least one further layer belongs to the group of layers detailed below, which group comprises: a protective layer that is composed of metal, a damping layer that is composed of a damping material ~~and preferably of a paper-like material~~, and a fastening layer that is composed of a fastening material ~~and preferably of an adhesive material~~.

7. (original) A data carrier, wherein the data carrier contains a module as claimed in claim 4.

8. (new) The module of claim 6 wherein the fastening material is an adhesive material.

9. (new) The lead-frame configuration of claim 3 wherein the fastening material is an adhesive material.

10. (new) A lead-frame configuration that is in the form of a lead-frame strip, that has a frame base and that has a plurality of lead-frames that are connected to the frame base and that are situated next to one another in the longitudinal direction of the lead-frame strip, each of which lead-frames is intended to receive a chip wherein, each lead-frame has at least two connecting plates wherein there is provided for the lead-frames that are situated next to one another in the

longitudinal direction of the lead-frame strip a reinforcement strip that extends in the longitudinal direction of the lead-frame strip and is connected both to the frame base and to the connecting plates of each of the lead-frames that are situated next to one another in the longitudinal direction of the lead-frame strip.

11. (new) The lead-frame configuration of claim 10 wherein the connection between the connecting plates and the reinforcement strip is made by means of a layer of adhesive.

12. (new) The lead-frame configuration of claim 11 wherein the reinforcement strip is formed by a fiber-reinforced film of plastics material and wherein the layer of adhesive is produced by means of an adhesive that is suitable for transmitting shear forces that may occur in the region between the connecting plates on the one hand and the reinforcement strip on the other hand

13. (new) A lead-frame configuration as claimed in claim 12, wherein at least one further layer is provided on the reinforcement strip formed by a fiber-reinforced film of plastics material.

14. (new) A lead-frame configuration as claimed in claim 13, wherein at least one further layer is provided on the reinforcement strip formed by a fiber-reinforced film of plastics material, which at least one further layer belongs to the group of layers detailed below, which group comprises: a protective layer that is composed of metal, a damping layer that is composed of a damping material, and a fastening layer that is composed of a fastening material.